RHF1401

Rad-hard 14-bit 20 Msps A/D converter

Ceramic SO-48 package

The upper metallic lid is not electrically connected to any pins, nor to the IC die inside the package.

Applications

- Digital communication satellites
- Space data acquisition systems
- Aerospace instrumentation
- Nuclear and high-energy physics

Description

The RHF1401 is a 14-bit analog-to-digital converter that uses pure CMOS 0.25 µm technology combining high performance and very low power consumption.

The RHF1401 is based on a pipeline structure and digital error correction to provide excellent static linearity. Specifically designed to optimize power consumption, the device only dissipates 85 mW at 20 Msps, while maintaining a high level of performance. The device also integrates a proprietary track-and-hold structure to ensure a large effective resolution bandwidth.

Voltage references are integrated in the circuit to simplify the design and minimize external components. A tri-state capability is available on the outputs to allow common bus sharing. A data-ready signal, which is raised when the data is valid on the output, can be used for synchronization purposes.

The RHF1401 has an operating temperature range of -55° C to +125° C and is available in a small 48-pin ceramic SO-48 package.

Features

- Qml-V qualified, smd 5962-06260
- Rad hard: 300 kRad(Si) TID
- Failure immune (SEFI) and latch-up immune (SEL) up to 120 MeV-cm^2/mg at 2.7 V and 125° C
- Hermetic package
- Tested at F_s = 20 Msps
- Low power: 85 mW at 20 Msps
- Optimized for 2 Vpp differential input
- High linearity and dynamic performances
- 2.5 V/3.3 V compatible digital I/O
- Internal reference voltage with external reference option

Table 1. Device summary

Order code	SMD pin	Quality level	Package	Lead finish	Mass	Temp range
RHF1401KSO1	-	Engineering model	SO-48	Gold	1.1 g	-55 °C to +125 °C
RHF1401KSO-01V	5962F0626001VXC	QMLV-Flight				

This is information on a product in full production.

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1.1 Block diagram

Figure 1. RHF1401 block diagram

1.2   Pin connections

Figure 2. Pin connections (top view)

GNDBI	1	48	DGND
GNDBE	2	47	DGND
VCCBE	3	46	CLK
NC	4	45	DGND
NC	5	44	DVCC
OR	6	43	DVCC
(MSB)D13	7	42	AVCC
D12	8	41	AVCC
D11	9	40	AGND
D10	10	39	INCM
D9	11	38	AGND
D8	12	37	VINB
D7	13	36	AGND
D6	14	35	VIN
D5	15	34	AGND
D4	16	33	VREFM
D3	17	32	VREFP
D2	18	31	IPOL
D1	19	30	AGND
(LSB)D0	20	29	AVCC
DR	21	28	AVCC
VCCBE	22	27	DFSB
GNDBE	23	26	OEB
VCCBI	24	25	REFMODE
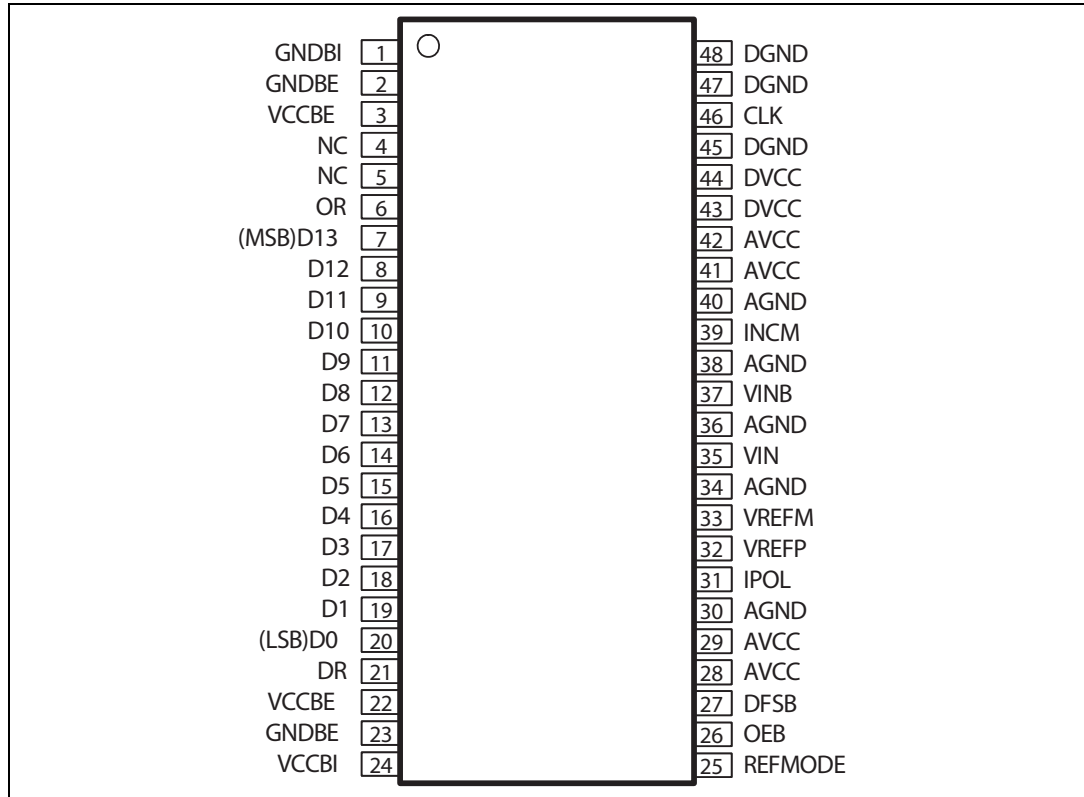
1.3 Pin descriptions

Table 2. Pin descriptions

Pin	Name	Description	Observations	Pin	Name	Description	Observations
1	GNDBI	Digital buffer ground	0 V	25	REFMODE	Ref. mode control input	2.5 V/3.3 V CMOS input
2	GNDBE	Digital buffer ground	0 V	26	OEB	Output enable input	2.5 V/3.3 V CMOS input
3	VCCBE	Digital buffer power supply	2.5 V/3.3 V	27	DFSB	Data format select input	2.5 V/3.3 V CMOS input
4		NC	Not connected to the dice	28	AVCC	Analog power supply	2.5 V
5		NC	Not connected to the dice	29	AVCC	Analog power supply	2.5 V
6	OR	Out of range output	CMOS output (2.5 V/3.3 V)	30	AGND	Analog ground	0 V
7	D13(MSB)	Most significant bit output	CMOS output (2.5 V/3.3 V)	31	IPOL	Analog bias current input	
8	D12	Digital output	CMOS output (2.5 V/3.3 V)	32	VREFP	Top voltage reference	Can be external or internal
9	D11	Digital output	CMOS output (2.5 V/3.3 V)	33	VREFM	Bottom voltage reference	0 V
10	D10	Digital output	CMOS output (2.5 V/3.3 V)	34	AGND	Analog ground	0 V
11	D9	Digital output	CMOS output (2.5 V/3.3 V)	35	VIN	Analog input	1 V_{pp}
12	D8	Digital output	CMOS output (2.5 V/3.3 V)	36	AGND	Analog ground	0 V
13	D7	Digital output	CMOS output (2.5 V/3.3 V)	37	VINB	Inverted analog input	1 V_{pp}
14	D6	Digital output	CMOS output (2.5 V/3.3 V)	38	AGND	Analog ground	0 V
15	D5	Digital output	CMOS output (2.5 V/3.3 V)	39	INCM	Input common mode	Can be external or internal
16	D4	Digital output	CMOS output (2.5 V/3.3 V)	40	AGND	Analog ground	0 V
17	D3	Digital output	CMOS output (2.5V /3.3 V)	41	AVCC	Analog power supply	2.5 V
18	D2	Digital output	CMOS output (2.5 V/3.3 V)	42	AVCC	Analog power supply	2.5 V
19	D1	Digital output	CMOS output (2.5 V/3.3 V)	43	DVCC	Digital power supply	2.5 V
20	D0(LSB)	Digital output LSB	CMOS output (2.5 V/3.3 V)	44	DVCC	Digital power supply	2.5 V
21	DR	Data ready output[1]	CMOS output (2.5 V/3.3 V)	45	DGND	Digital ground	0 V
22	VCCBE	Digital buffer power supply	2.5 V/3.3 V	46	CLK	Clock input	2.5 V compatible CMOS input
23	GNDBE	Digital buffer ground	0 V	47	DGND	Digital ground	0 V
24	VCCBI	Digital buffer power supply	2.5 V	48	DGND	Digital ground	0 V

1. See load considerations in *Section 2.2: Timing characteristics*.

1.4   Equivalent circuits

Figure 3. Analog inputs	Figure 4. Output buffers

Figure 3. Analog inputs

$Z_{IN} = 1/(C_S.F_S)$

VIN or VINB

AVCC

AGND

7pF (pad)

INCM

Figure 4. Output buffers

VCCBE

OEB

Data

GNDBE

VCCBE

GNDBE

D0 ...D13

7 pF (pad)

AM04558

Figure 5. Clock input

DVCC

CLK

7 pF (pad)

DGND

AM04559

Figure 6. Data format input

VCCBE

DFSB

7 pF (pad)

GNDBE

AM04560

Figure 7. Reference mode control input

VCCBE

REFMODE

7 pF (pad)

GNDBE

AM04561

Figure 8. Output enable input

VCCBE

OEB

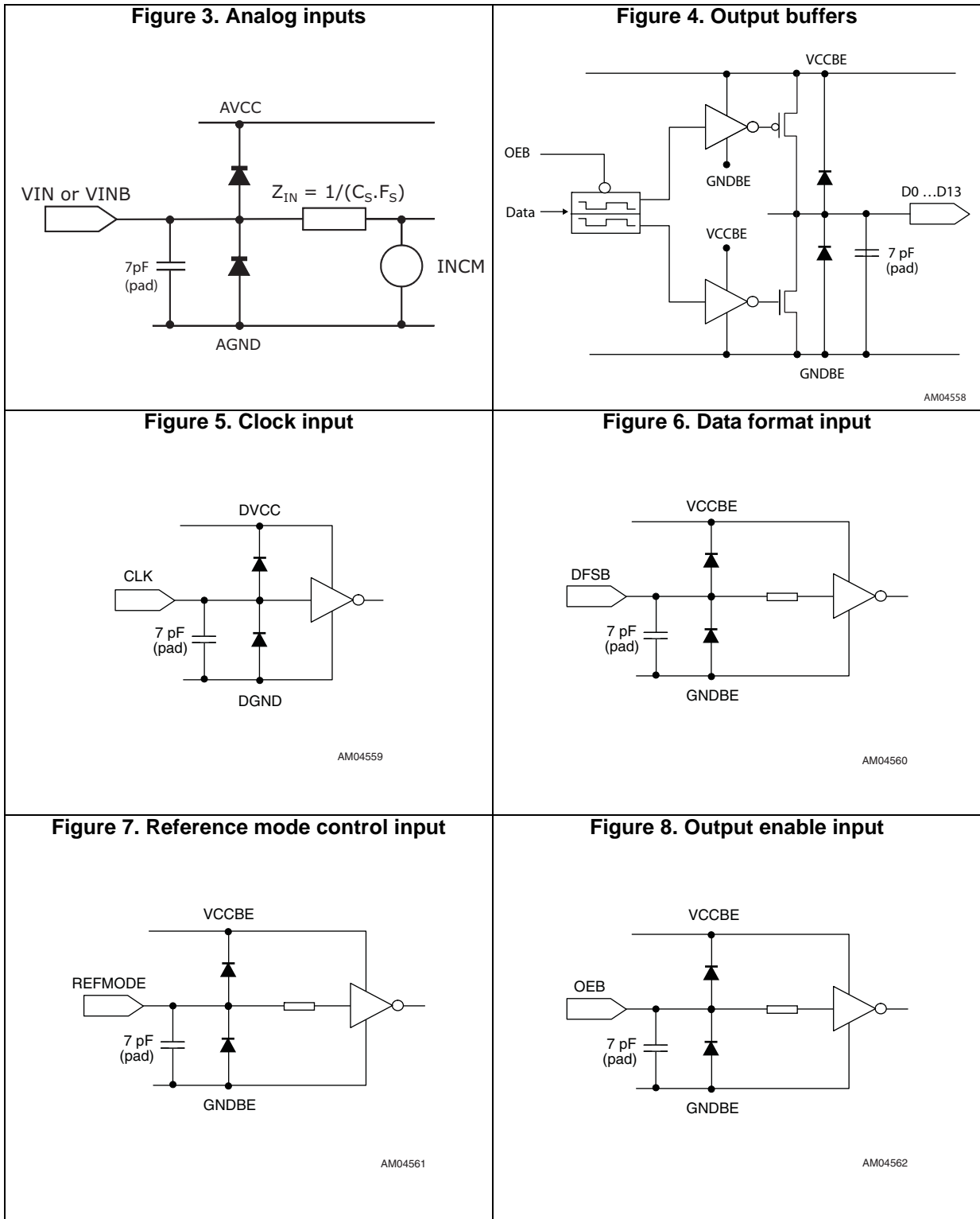7 pF (pad)

GNDBE

AM04562
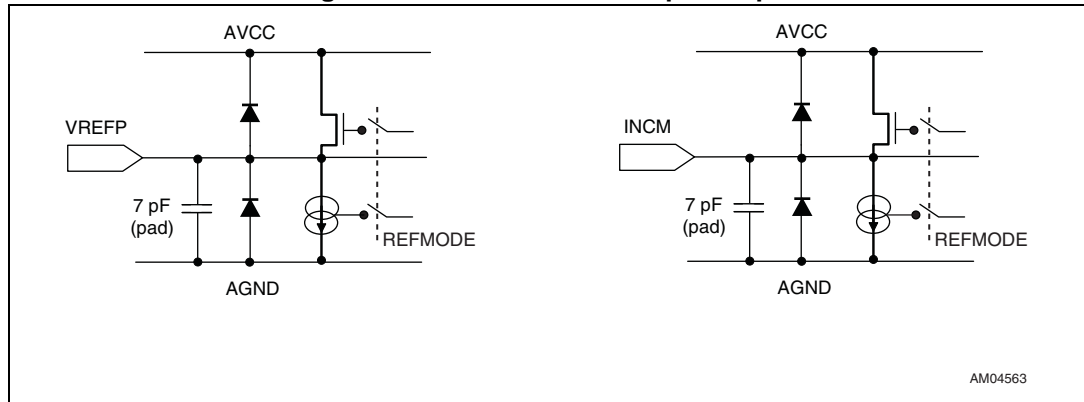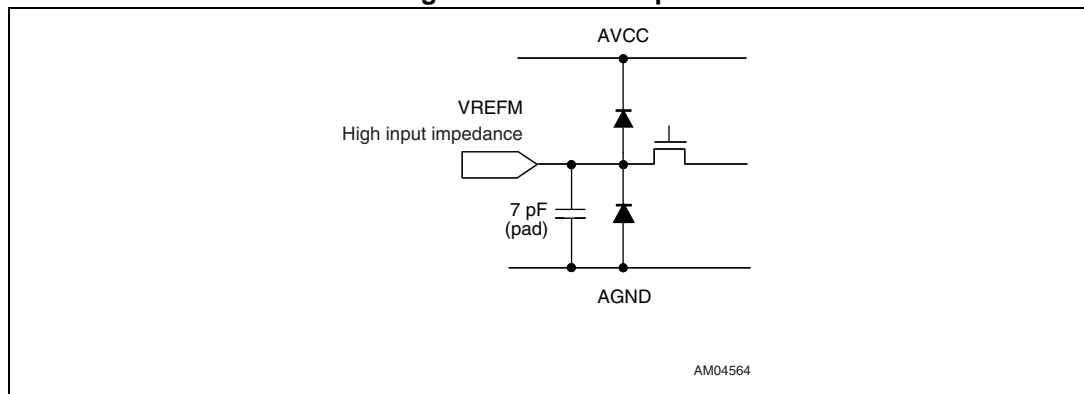
Figure 9. VREFP and INCM input/output

Figure 10. VREFM input

2   Electrical characteristics

2.1   Absolute maximum ratings and operating conditions

Table 3. Absolute maximum ratings

Symbol	Parameter	Values	Unit
AV_{CC}	Analog supply voltage	3.3	V
DV_{CC}	Digital supply voltage	3.3	V
V_{CCBI}	Digital buffer supply voltage	3.3	V
V_{CCBE}	Digital buffer supply voltage	3.6	V
V_{IN} V_{INB}	Analog inputs: bottom limit -> top limit	-0.6 V -> AV_{CC}+0.6 V	V
V_{REFP} V_{INCM}	External references: bottom limit -> top limit	-0.6 V -> AV_{CC}+0.6 V	V
I_{Dout}	Digital output current	-100 to 100	mA
T_{stg}	Storage temperature	-65 to +150	°C
R_{thjc}	Thermal resistance junction to case	22	°C/W
R_{thja}	Thermal resistance junction to ambient	125	°C/W
ESD	HBM (human body model)[1]	2	kV

1. Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5 kW resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.

Table 4. Operating conditions

Symbol	Parameter	Min	Typ	Max	Unit
AV_{CC}	Analog supply voltage	2.3	2.5	2.7	V
DV_{CC}	Digital supply voltage	2.3	2.5	2.7	V
V_{CCBI}	Digital internal buffer supply	2.3	2.5	2.7	V
V_{CCBE}	Digital output buffer supply	2.3	2.5	3.4	V
V_{REFP}	Forced top voltage reference	0.5	1	1.3	V
V_{REFM}	Bottom external reference voltage	0	0	0.5	V
V_{REFP} - V_{REFM}	Difference between external reference voltage	0.3			V
V_{INCM}	Forced common mode voltage	0.2	0.5	1.1	V
V_{IN} or V_{INB}	Max. voltage versus GND		1	1.6	V
	Min. voltage versus GND	-0.2	GND		V
DFSB					
REFMODE	Digital inputs	0		V_{CCBE}	V
OEB					

2.2   Timing characteristics

Table 5. Timing characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
DC	Clock duty cycle	F_S = 20 Msps	45	50	65	%
T_{od}	Data output delay (fall of clock to data valid) [1]	10 pF load capacitance	5	7.5	13	ns
T_{pd}	Data pipeline delay[2]	Duty cycle = 50%	7.5	7.5	7.5	cycles
T_{on}	Falling edge of OEB to digital output valid data			1		ns
T_{off}	Rising edge of OEB to digital output tri-state			1		ns
T_{rD}	Data rising time	10 pF load capacitance		6		ns
T_{fD}	Data falling time	10 pF load capacitance		3		ns

1. As per *Figure 11*.

2. If the duty cycle does not equal 50%: T_{pd} = 7 cycles + CLK pulse width.

Figure 11. Timing diagram
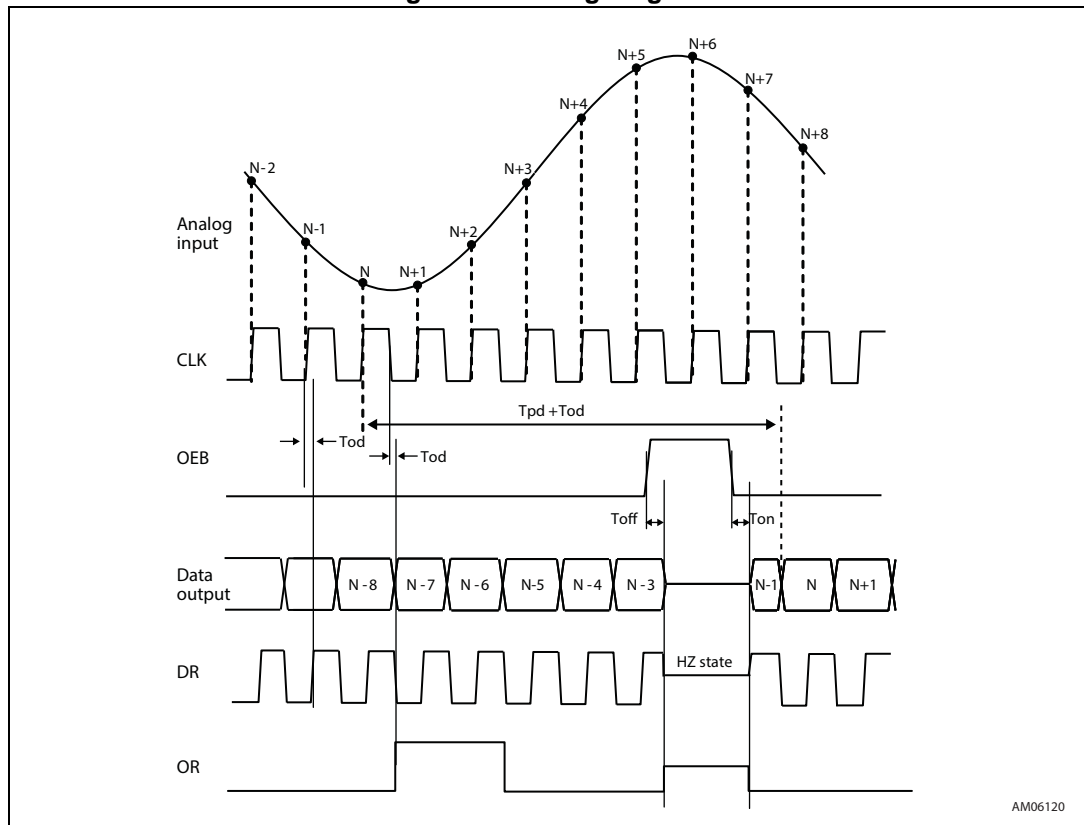
The input signal is sampled on the rising edge of the clock while the digital outputs are synchronized on the falling edge of the clock. The duty cycles on DR and CLK are the same.

The rising and falling edges of the OR pin are synchronized with the falling edge of the DR pin.

2.3 Electrical characteristics (after 300 kRad)

Unless otherwise specified, the test conditions in the following tables are:
AVCC = DVCC = VCCBI =VCCBE = 2.5 V, F_s=20 Msps, F_{IN}= 15 MHz, V_{IN} at -1 dBFS,
VREFP = 1 V, INCM = 0.5 V, VREFM = 0 V, T_{amb} = 25 °C.

Table 6. Analog inputs

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{IN}-V_{INB}	Full-scale reference voltage (FS)[1]	VREFP = 1 V (forced) VREFM = 0 V		2		V_{pp}
C_{IN}	Input capacitance			7		pF
Z_{IN}	Input impedance vs. INCM[2]	F_s = 20 Msps		21		kΩ
ERB	Effective resolution bandwidth[1]			70		MHz

1. See *Section 4: Definitions of specified parameters* for more information.

2. Zin = 1/(Fs x C) with C = 2.4 pF

Table 7. Internal reference voltage[1]

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
R_{out}	Output resistance of internal reference	REFMODE = 0 internal reference on		30		Ω
		REFMODE = 1 internal reference off		7.5		kΩ
V_{REFP}	Top internal reference voltage	REFMODE = 0	0.76	0.84	0.95	V
V_{INCM}	Input common mode voltage	REFMODE = 0	0.40	0.44	0.50	V

1. Refer to *Section 3.2: Driving the analog input: How to correctly bias the RHF1401* for correct biasing of RHF1401

Table 8. External reference voltage[1]

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{REFP}	Forced top reference voltage	REFMODE = 1	0.5		1.3	V
V_{REFM}	Forced bottom ref voltage	REFMODE = 1	0		0.5	V
V_{INCM}	Forced common mode voltage	REFMODE = 1	0.2		1.1	V

1. See *Figure 22* & *Figure 23*
   Refer to *Section 3.2: Driving the analog input: How to correctly bias the RHF1401* for correct biasing of RHF1401

Table 9. Static accuracy

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
DNL	Differential non-linearity	F_{in} = 1.5 Msps V_{in} at +1 dBFS F_s = 1.5 Msps		±0.4		LSB
INL	Integral non-linearity			±3		LSB
	Monotonicity and no missing codes			Guaranteed		
OE	Offset Error	Fs = 5 Msps		±100		LSB
GE	Gain Error	Fs = 5 Msps		±0.3		%

Table 10. Digital inputs and outputs

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
Clock input						
CT	Clock threshold	DV_{CC} = 2.5 V		1.25		V
CA	Square clock amplitude (DC component = 1.25 V)	DV_{CC} = 2.5 V	0.8		2.5	Vpp
Digital inputs						
V_{IL}	Logic "0" voltage	V_{CCBE} = 2.5 V	0		0.25 x V_{CCBE}	V
V_{IH}	Logic "1" voltage	V_{CCBE} = 2.5 V	0.75 x V_{CCBE}		V_{CCBE}	V
Digital outputs						
V_{OL}	Logic "0" voltage	I_{OL} = -10 µA		0	0.25	V
V_{OH}	Logic "1" voltage	I_{OH} = 10 µA	V_{CCBE} -0.25			V
I_{OZ}	High impedance leakage current	OEB set to V_{IH}	-15		15	µA
C_L	Output load capacitance	High CLK frequencies			15	pF

Table 11. Dynamic characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
SFDR	Spurious free dynamic range	F_{in} = 15 MHz F_s = 20 Msps V_{in} at -1 dBFS internal references C_L = 6 pF	70	91		dBFS
SNR	Signal to noise ratio		66	70		dB
THD	Total harmonic distortion		70	86		dB
SINAD	Signal to noise and distortion ratio		65	70		dB
ENOB	Effective number of bits		10.6	11.5		bits

Higher values of SNR, SINAD and ENOB can be obtained by increasing the full-scale range of the analog input **if the sampling frequency and the biasing of RHF1401 allow it**.

3 User manual

3.1 Optimizing the power consumption

The polarization current in the input stage is set by an external resistor (R_{pol}). When selecting the resistor value, it is possible to optimize the power consumption according to the sampling frequency of the application. For this purpose, an external R_{pol} resistor is placed between the IPOL pin and the analog ground.

The values in *Figure 12* are achieved with VREFP = 1 V, VREFM = 0 V, INCM = 0.5 V and the input signal is 2 Vpp with a differential DC connection. If the conditions are changed, the R_{pol} resistor varies slightly but remains in the domain described in *Figure 12*.

Figure 12 shows the optimum R_{pol} resistor value to obtain the best ENOB value. It also shows the minimum and maximum values to get good results. ENOB decreases by approximately 0.2 dB when you change R_{pol} from optimum to maximum or minimum.

If R_{pol} is higher than the maximum value, there is not enough polarization current in the analog stage to obtain good results. If R_{pol} is below the minimum, THD increases significantly.

Therefore, the total dissipation can be adjusted across the entire sampling range to fulfill the requirements of applications where power saving is critical.

For sampling frequencies below 2 MHz, the optimum resistor value is approximately 80 kOhms.

Figure 12. R_{pol} values vs. F_s
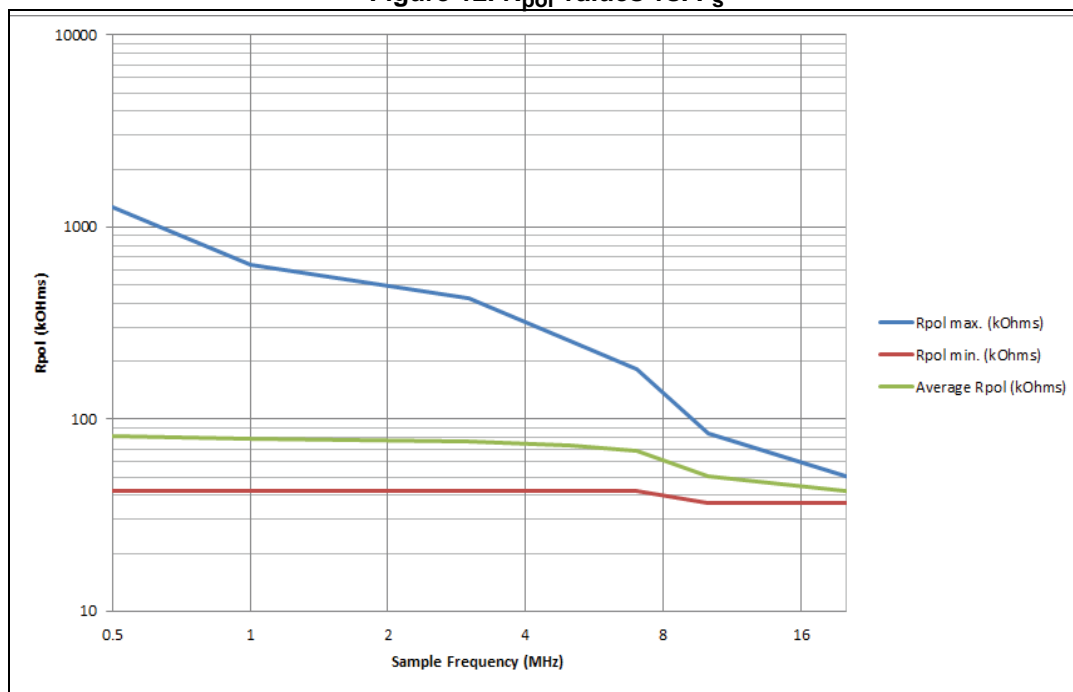
The power consumption depends on the R_{pol} value and the sampling frequency. In *Figure 13*, it is shown with the internal references disabled (REFMODE = 1) and R_{pol} defined in *Figure 12* as the optimum.

Figure 13. Power consumption values vs. F$_s$ with internal references disabled
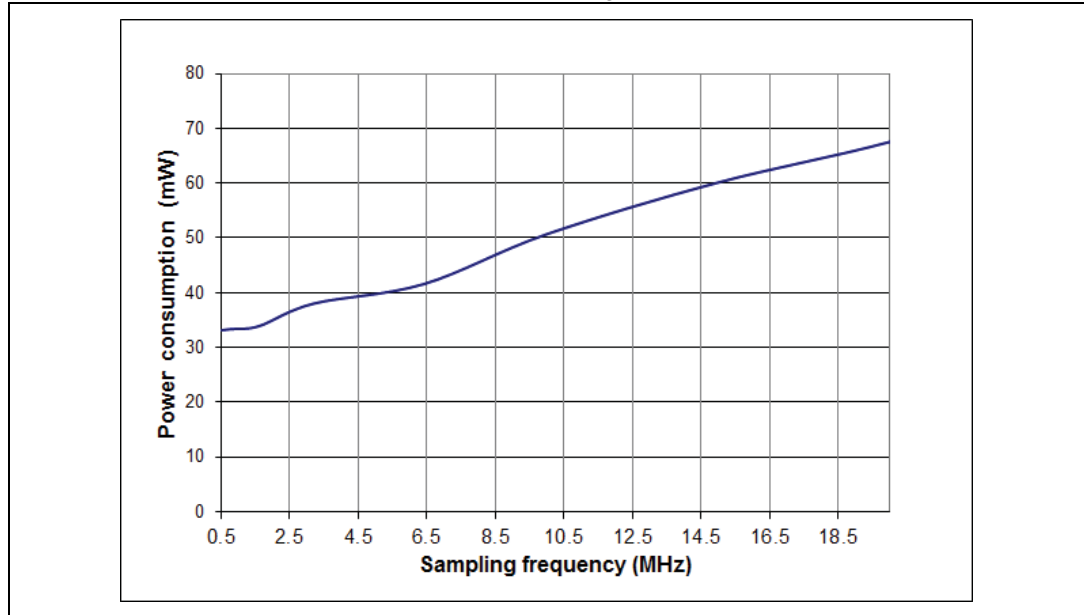
3.2 Driving the analog input: How to correctly bias the RHF1401

It's mandatory to follow some simple biasing rules to reach optimal performance when driving the RHF1401.

DC biasing and the AC swing must be considered in order to keep the analog input in the correct range. Let's define some parameters:

Definition 1: The common mode of the input signal is:

$$CMinput = \frac{(Vin + Vinb)}{2}$$

Definition 2: The common mode of reference voltage is:

$$CMref = \frac{(Vrefp + Vrefm))}{2}$$

To have correct biasing of RHF1401, **this condition must be respected at all times**:

$$CMinput \leq CMref + 0.2V$$

Please note that the INCM value is not a parameter of the previous equations. INCM is an input/output that's used to bias internal OTA amplifiers. So INCM can be any value from *Table 4*.

However, if the INCM value is used to bias analog inputs (Vin and Vinb), Cminput becomes dependent of INCM. In this case, the setting of INCM must be chosen to respect the equation:

$$CMinput \leq CMref + 0.2V$$

Now let's see what happens when the RHF1401 is driven in differential mode and single-ended mode. We will use a sinusoidal input signal for ease of computation, but the results presented after can be easily extrapolated to another kind of signal shape.

3.2.1 Differential mode biasing

In differential mode we have

- Vin = Vbias + A sin(ωt) and Vinb = Vbias – A sin(ωt) with A = peak of input signal.
- Vbias can be provided by the source signal or by INCM. It's the DC biasing of the sinusoidal input signal.

As by definition, AC components are in opposite phase for Vin and Vinb, at any time on the signal we have CMinput = Vbias.

In differential mode, to keep a safe operation of RHF1401 analog inputs, we have to respect :
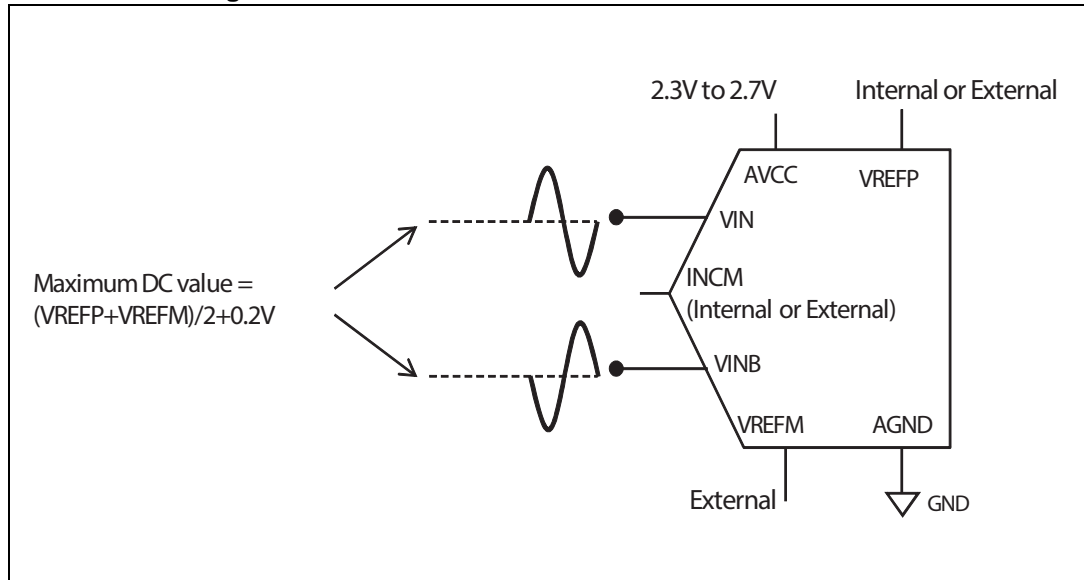
$$Vbias \leq CMref + 0.2V$$

and referring to *Table 4* for the maximum input signal allowed we have:

$$A + Vbias \leq 1.6V$$

and

$$Vbias - A \geq -0.2V$$

Figure 14. RHF1401 in recommended differential mode

3.2.2 Single-ended mode biasing

In single-ended mode, the biasing consideration is different because, as we will see, CMinput is no longer constant but dependent on the amplitude of the input signal. This dependency limits considerably the possibilities of single-ended use.

Please note also that in the demonstration below, Vin is variable and Vinb is fixed, but the opposite is possible simply by exchanging Vin and Vinb in the equations.

Let's take a typical situation with:

Vin = Vbias + A sin(ωt) and Vinb = Vbias with A = peak of input signal.

Vbias can be provided by the source signal or by INCM which is the DC biasing of sinusoidal input signal.

In this case,

$$CMinput = \frac{(A \times \sin\omega t)}{2} + Vbias$$

and CMinput is totally dependent on the amplitude of the input signal.

In addition, as the following relationship is still true:

$$CMinput \leq CMref + 0.2V$$

now we have:

$$\frac{(A \times \sin\omega t)}{2} + Vbias \leq CMref + 0.2V$$

and of course and referring to *Table 4* for the maximum input signal allowed we have:

$$A + Vbias \leq 1.6V$$

and

$$Vbias - A \geq -0.2V$$

So, depending on the settings of Vrefp, Vrefm, the following condition

$$\frac{(A \times \sin\omega t)}{2} + Vbias \leq CMref + 0.2V$$

can occur very soon before reaching the full-scale input of RHF1401.

<u>Example</u>: you have an input signal in single-ended that maximizes the full swing authorized for RHF1401 input -0.2 V to 1.6 V which gives 1.8 Vpp in single-ended. The biasing settings are as follows:

- As the full scale of ADC is defined by (Vrefp – Vrefm)x2, if Vrefm = 0 V, we have 2xVrefp =1.8 V then Vrefp = 0.9 V

- Vbias = 1.6 V – 1.8V/2 = 0.7 V, then Vin = 0.7 V + (1.8V/2)xsin(ωt) = 0.7 V + 0.9Vxsin(ωt), then A = 0.9 V

- Vinb = Vbias Vin= 0.7 V

With these setttings, we can calculate CMref + 0.2 V = 0.65 V and CMinput = 0.7 V + (0.9Vxsin(ωt))/2. Then, CMinput is maximum when sin(ωt) = 1 that gives CMinputmax.= 1.15 V which is far beyond the limit of 0.65 V previously calculated. The range of Vin allowed is -0.2 V to 0.65 V that is even below the half scale requested initially.

A solution to this problem would be to increase the CMref value which is done by increasing Vrefm and Vrefp.

Let's take Vrefm = 0.5 V and calculate Vrefp to have CMref + 0.2 V = 1.15 V.

The solution is Vrefp = 1.4 V that is 0.1 V higher than the maximum allowed in *Table 4*.

So, the only way is to reduce the input swing in accordance with the maximum Vrefp and Vrefm allowed.

With Vrefp = 1.3 V, Vrefm = 0.5 V, CMref + 0.2 V = 1.1 V. CMinput maximum = 1.1 V that gives Vbias = 1.1 V - A/2. With A = 0.8 V, Vbias = 0.7 V => Vinpp = 1.6 V, A + Vbias = 1.5 V, Vbias - A = -0.1 V. By reducing the input amplitude by 200 mVpp, we are able to find a solution that fits the limits given in *Table 4*.

With this example, we can see that the main limitation in single-ended mode, on the condition to maximize the full digital swing (0 to 2^{14}), will come from the CMinput maximum vs. Vrefp and Vrefm allowed.

We can see also, with the previous example, to fit the large full swing requested, you need three different biasing values (Vrefp, Vrefm, Vbias = INCM) or four if the Vbias value is not compatible with the INCM range allowed.

More generally, if the number of different biasing values is a problem, it's possible to work in single-ended with two different biasing values. By setting INCM = Vrefm = Vbias = Vinb = Vrefp/2, you can have a "simple" single-ended as represented in *Figure 15*.

Figure 15. RHF1401 in recommended single-ended mode
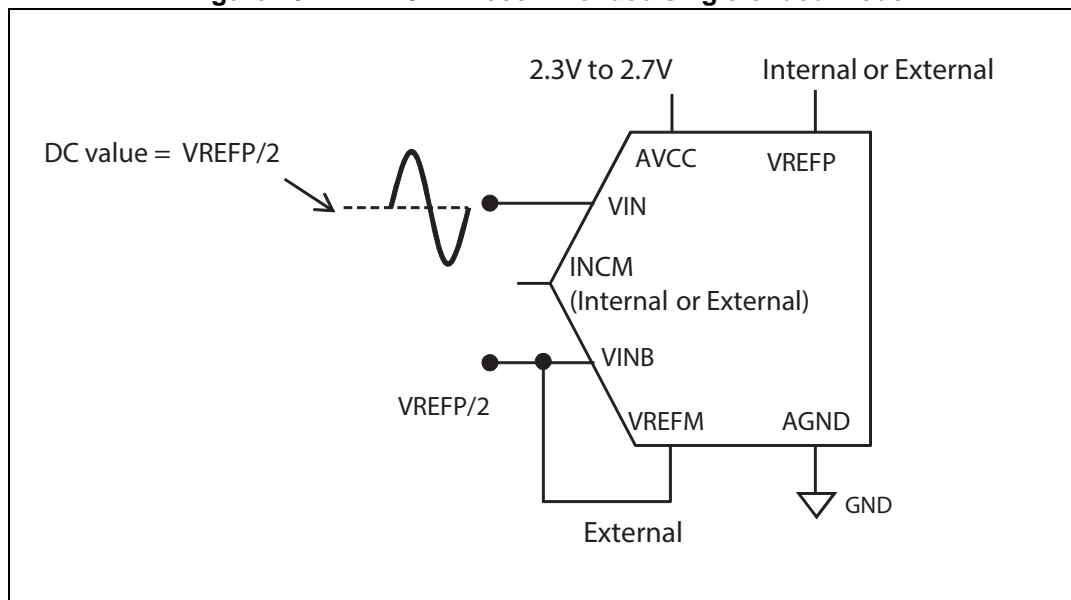
However, we can calculate that the main limitation will come from the Vrefm maximum value = 0.5 V.

Let's take Vrefm = INCM = Vbias = Vinb = 0.5 V and Vrefp = 1 V => the input swing allowed on Vin is 1 Vpp centered at 0.5 V => A = 0.5 V

Here, CMref = 0.75 V and CMinput maximum = 0.75 V. So for an input voltage Vin from 0 V to 1 V, the output code will vary from 0 to 2^{14}.

Now, let's see how much the maximum input amplitude Vin can be to go in saturation mode (bit OR set to 1).

As CMref + 0.2 V = 0.95 V, the theoretical input voltage Vin allowed can be: Vin = 0.5 V + 0.9 V sin(ωt).

Here, CMinput maximum = 0.95 V but A + Vbias = 1.4 V and Vbias - A = -0.4 V. The -0.4 V is a problem because only -0.2 V is allowed. Finally, the practical input voltage Vin is: Vin = 0.5 V + 0.7 V sin(ωt) => CMinput maximum = 0.85 V, A + Vbias = 1.2 V and Vbias - A = -0.2 V.

Particular case where Vrefm = 0 V and cannot be changed

In some applications, a dual mode can be requested: differential mode and single-ended mode with a preference for differential mode first.

Let's take a typical example for differential mode:

Vrefp = 1 V, Vrefm = 0 V, Vbias = INCM = 0.5 V. This safe configuration gives a full scale at 2 Vpp (1 Vpp on each input with Vbias = 0.5 V and A = 0.5 V). Here you can use all digital output codes from 0 to 2^{14}.

Now let's go to single-ended mode by keeping Vrefp = 1 V, Vrefm = 0 V, Vbias = INCM = Vinb = 0.5 V. What would be the maximum swing allowed on Vin and what would be the resulting code? So:

Full scale = 2 x (Vrefp - Vrefm) = 2 V

CMref = 0.5 V and CMref + 0.2 V = 0.7 V

By definition, the limitation on the lower side is -0.2 V

The limitation of Vin on the upper side is given by this equation:

$$\frac{(\mathrm{Vinmax} + \mathrm{Vbias})}{2} \leq 0.7\mathrm{V}$$

So Vinmax = 0.9 V.
Finally

$$-0.2\mathrm{V} \leq \mathrm{Vin} \leq 0.9\mathrm{V}$$

that gives:

$$5734 \leq \text{Output Code (decimal)} \leq 11468$$

Here, the full scale is not usable but a limited range only.

3.2.3 INCM biasing

As previously discussed, INCM is an input/output that's used to bias the internal OTA amplifiers of the RHF1401. So INCM can be any value from *Table 4*.

However, depending on the INCM value, the performance can change slightly. For RHF1401 and for INCM from 0.4 V to 1 V, no impact on performances can be observed.

For INCM from 0.2 V to 0.4 V and 1 V to 1.1 V, it's possible to have, under boundary conditions, a typical loss of one bit of ENOB. So, if you have the choice, keep the value of INCM in the range 0.4 V to 1 V.

3.3 Output code vs. analog input and mode usage

Whatever the configuration chosen (differential or single-ended), the two following equations are always true for RHF1401:

- The full scale of the analog input is defined by: Full scale = 2 x (Vrefp - Vrefm)
- The output code is defined also as: Output code = f(Vin - Vinb) vs. Full scale

Finally we got for DFSB = 1:

$$\text{Output code (14 bits)} = \frac{\mathrm{3FFF} \times (\mathrm{Vin} - \mathrm{VinB})}{2 \times (\mathrm{Vrefp} - \mathrm{Vrefm})} + \mathrm{1FFF}$$

and for DFSB = 0:

$$\text{Output code (14 bits)} = \frac{\mathrm{3FFF} \times (\mathrm{Vin} - \mathrm{VinB})}{2 \times (\mathrm{Vrefp} - \mathrm{Vrefm})} + \mathrm{1FFF} + 2000$$
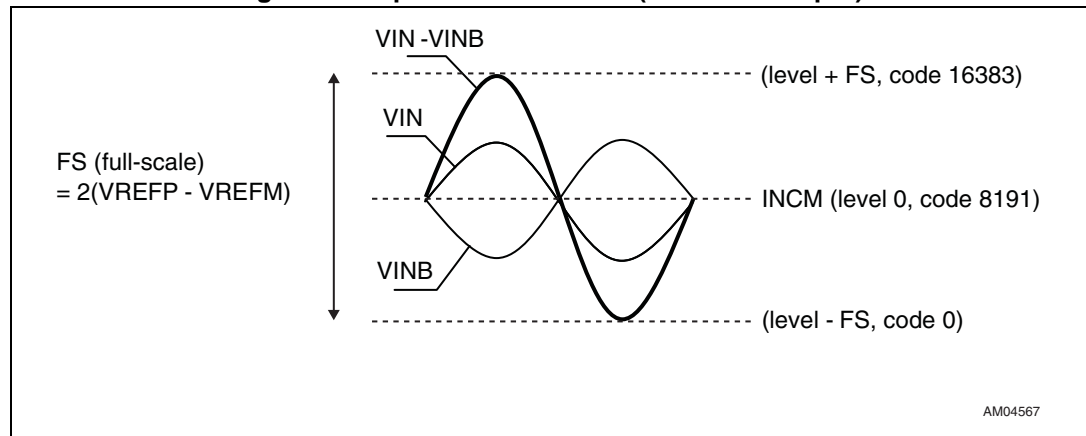
3.3.1 Differential mode output code

In this mode, the DC component of Vin and Vinb is naturally subtracted. We get the following table:

Table 12. Differential mode output codes

Vin - Vinb =	DFSB = 1	DFSB = 0
+ (VREFP-VREFM)	3FFF	1FFF
0	1FFF	3FFF
- (VREFP-VREFM)	0000	2000

If INCM = Vbias we have *Figure 16*:

Figure 16. Equivalent Vin - Vinb (differential input)

3.3.2 Single-ended mode output code

In single-ended mode, Vin or Vinb is constant and equal to Vbias.

If Vin = Vbias + A sin(ωt) and Vinb = Vbias with A = peak of input signal, then (Vin - Vinb) = A sin(ωt) and A = (Vrefp - Vrefm) for maximum swing on input.

Table 13. Single-ended mode output codes with Vinb = Vbias and A = (Vrefp - Vrefm)

Vin =	DFSB = 1	DFSB = 0
Vbias + (VREFP-VREFM)	3FFF	1FFF
Vbias	1FFF	3FFF
Vbias - (VREFP-VREFM)	0000	2000

3.4 Design examples

The RHF1401 is designed to obtain optimum performance when driven on differential inputs with a differential amplitude of two volts peak-to-peak (2 V_{pp}). This is the result of 1 V_{pp} on the Vin and Vinb inputs in phase opposition (*Figure 17*).

For all input frequencies, it is mandatory to add a capacitor on the PCB (between Vin and Vinb) to cut the HF noise. The lower the frequency, the higher the capacitor.

The RHF1401 is specifically designed to meet sampling requirements for intermediate frequency (IF) input signals. In particular, the track-and-hold in the first stage of the pipeline is designed to minimize the linearity limitations as the analog frequency increases.

Differential mode

Figure 17 shows an example of how to drive the RHF1401 in differential and DC coupled.

Figure 17. Example 2 V$_{pp}$ differential input
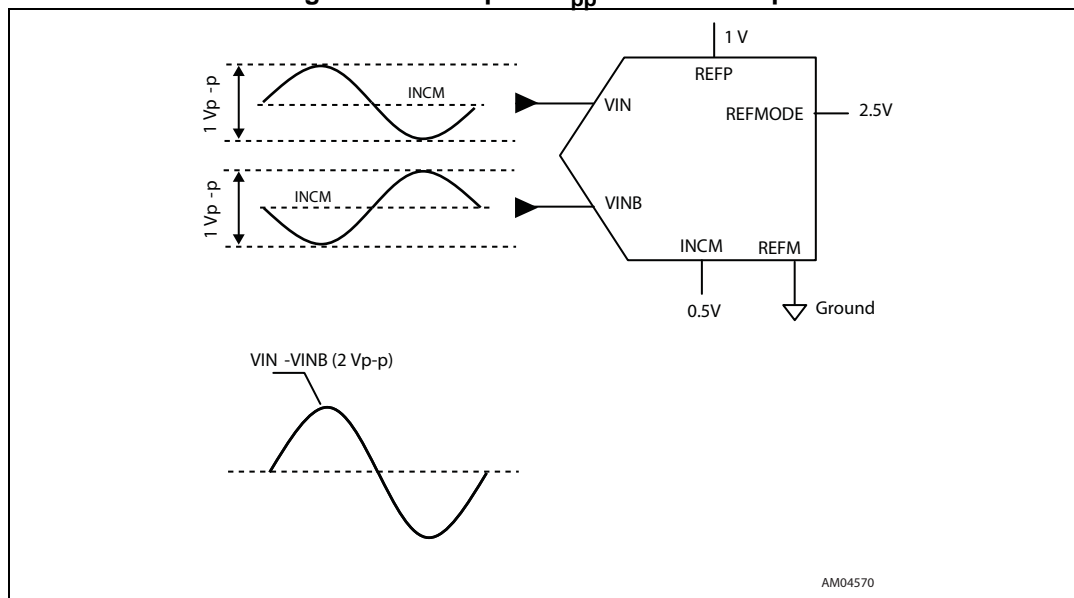

Figure 18 shows an isolated differential input solution. The input signal is fed to the transformer's primary, while the secondary drives both ADC inputs. The transformer must be matched with the generator output impedance: 50 Ω in this case for proper matching with a 50 Ω generator. The tracks between the secondary and Vin and Vinb pins must be as short as possible.

Figure 18. Differential implementation using a balun
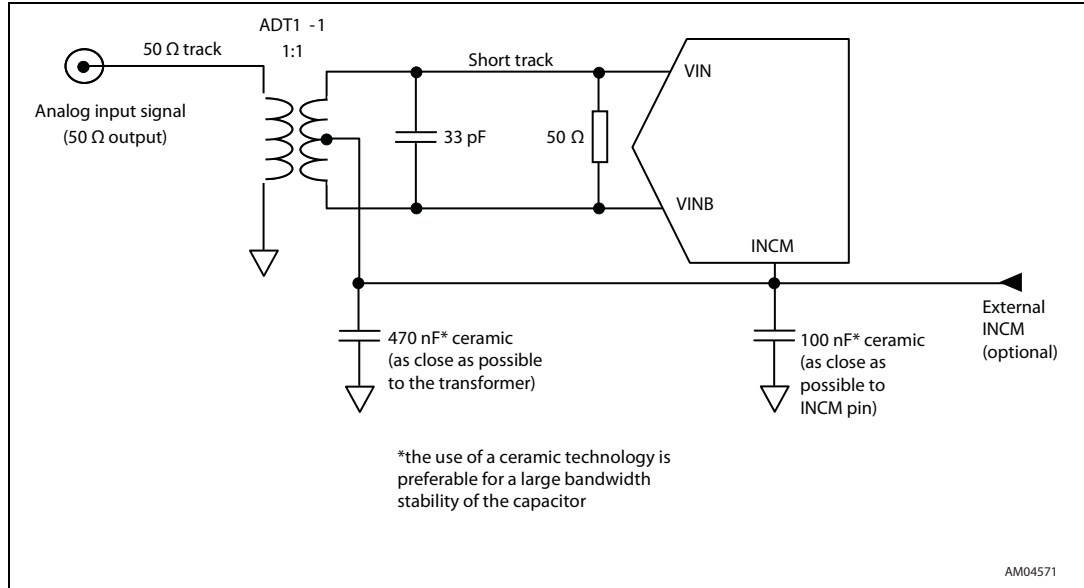
The input common-mode voltage of the ADC (INCM) is connected to the center tap of the transformer's secondary in order to bias the input signal around the common voltage (see *Table 7: Internal reference voltage*).The INCM is decoupled to maintain a low noise level on this node. Ceramic technology for decoupling provides good capacitor stability across a wide bandwidth.

Single-ended mode

Figure 19 shows an example of how to drive the RHF1401 in single-ended and DC coupled. This is the optimized configuration recommended. For more explanations, see *Chapter 3.2: Driving the analog input: How to correctly bias the RHF1401*

Figure 19. Optimized single-ended configuration (DC coupling)
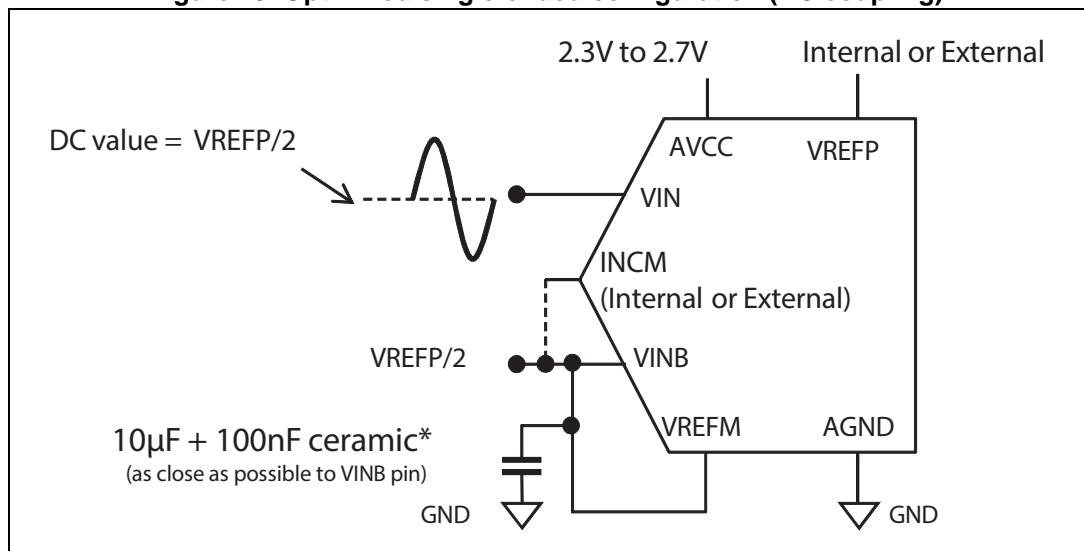
Note: **The use of ceramic technology is preferable to ensure large bandwidth stability of the capacitor.*

As some applications may require a single-ended input, it can be easily done with the configuration shown in *Figure 19* for DC coupling and *Figure 20* for AC coupling. However, with this type of configuration, a degradation in the rated performance of the RHF1401 may occur compared with a differential configuration. **You should expect a degradation of ENOB of about 2 bits compared to differential mode.** A sufficiently decoupled DC reference should be used to bias the RHF1401 inputs. An AC-coupled analog input can also be used and the DC analog level set with a high-value resistor R (10 kΩ) connected to a proper DC source. Cin and R behave like a high-pass filter and are calculated to set the lowest possible cut-off frequency.

Figure 20. AC-coupling single-ended input configuration
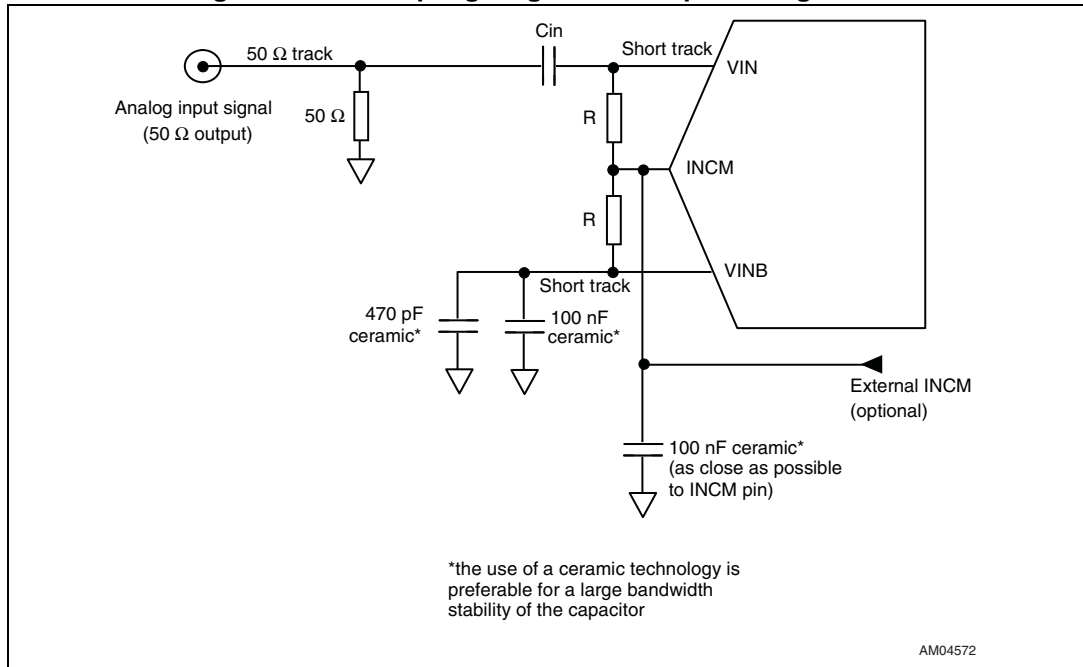
3.5 Reference connections

3.5.1 Internal voltage reference

In standard configuration, the ADC is biased with two internal voltage references: VREFP and INCM. They must be decoupled to minimize low and high frequency noise. When the REFMODE pin is set to 0, both internal voltage references are enabled and they can drive external components.

The VREFM pin has no internal reference and must be connected to a voltage reference. It is usually connected to the analog ground for differential mode and to Vrefp/2 for single-ended mode.

Figure 21. Internal voltage reference setting
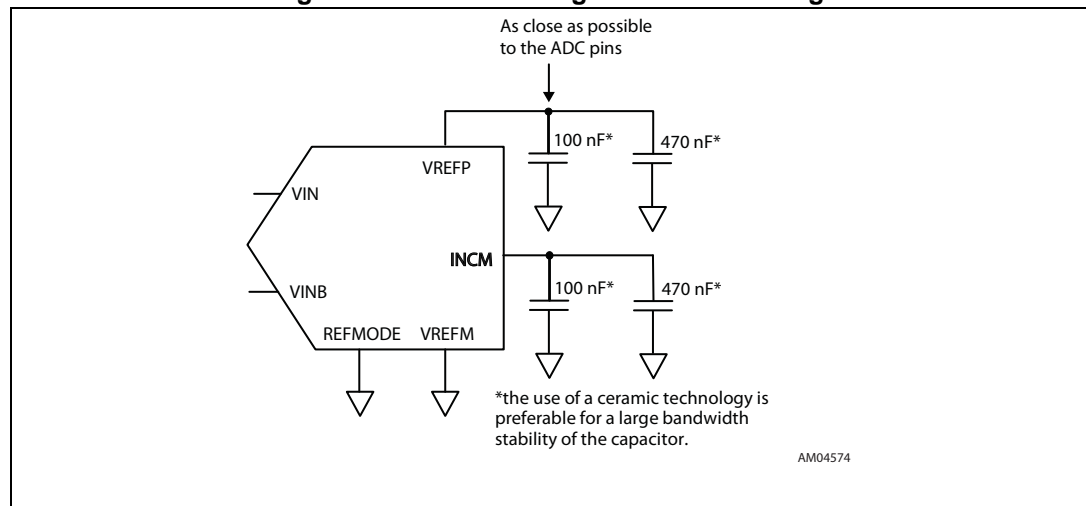
3.5.2 External voltage reference

External voltage references can be used for specific applications requiring better linearity, enhanced temperature behavior, or different voltage values (see *Table 7: Internal reference voltage*). Internal voltage references are disabled when the REFMODE pin is equal to 1. In this case, external voltage references must be applied to the device.

When internal voltage reference are disabled, ADC consumption is about 13 mA less than when they are enabled.

The external voltage references with the configuration shown in *Figure 22* and *Figure 23* can be used to obtain optimum performance. Decoupling is achieved by using ceramic capacitors, which provide optimum linearity versus frequency.
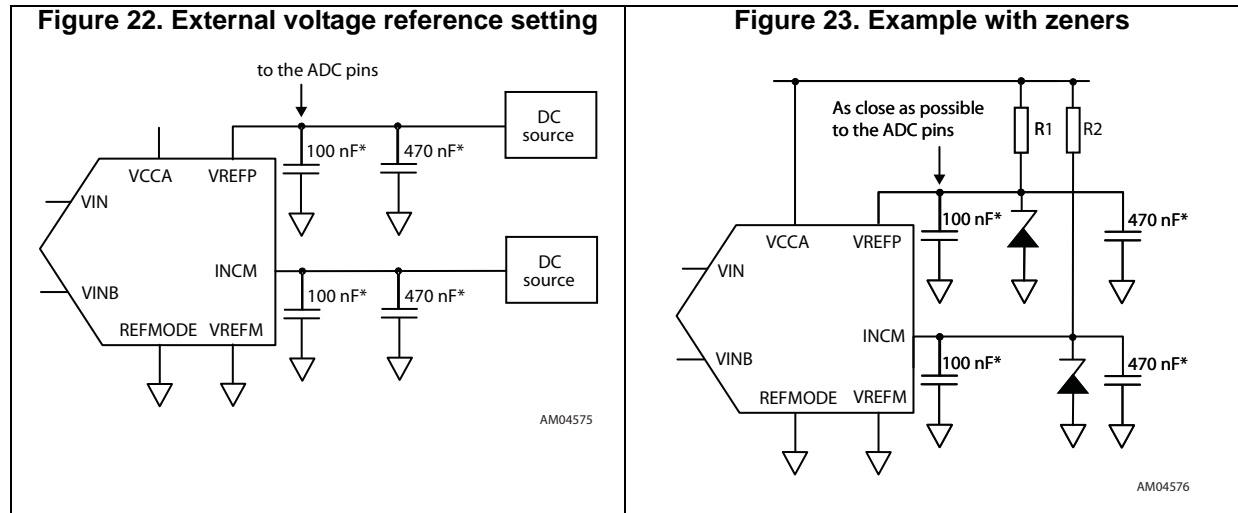
Figure 22. External voltage reference setting


Figure 23. Example with zeners

Note: **The use of ceramic technology is preferable to ensure large bandwidth stability of the capacitor.*

In multi-channel applications, the high impedance input (when REFMODE = 1) of the references allows one to drive several ADCs with only two voltage reference devices.

In differential mode the voltage of the analog input common mode (INCM) should be around $V_{REFP}/2$. Higher levels introduce more distortion.

3.6 Clock input

The quality of the converter very much depends on the accuracy of the clock input in terms of jitter. The use of a low-jitter, crystal-controlled oscillator is recommended.

The following points should also be considered.

- The clock's power supplies must be independent of the ADC's output supplies to avoid digital noise modulation at the output.
- When powered-on, the circuit needs several clock periods to reach its normal operating conditions.
- The square clock must respect *Table 5* and *Table 10*

The signal applied to the CLK pin is critical to obtain full performance from the RHF1401. It is recommended to use a square signal with fast transition times and to place proper termination resistors as close as possible to the device.

3.7 Reset of RHF1401

To reset the RHF1401, it's **mandatory** to apply several clock periods.

At power-up, without any clock signal applied to RHF1401, the device is not reset.

In this case, parameters like Vrefp, Incm and Rout will not be in line with values in *Table 7*.

3.8 Operating modes

Extra functionalities are provided to simplify the application board as much as possible. The operating modes offered by the RHF1401 are described in *Table 14*.

Table 14. RHF1401 operating modes

Inputs			Outputs		
Analog input differential amplitude	**DFSB**	**OEB**	**OR**	**DR**	**Most significant bit (MSB)**
(V_{IN}-V_{INB}) above maximum range	H	L	H	CLK	D13
	L	L	H	CLK	D13 complemented
(V_{IN}-V_{INB}) below minimum range	H	L	H	CLK	D13
	L	L	H	CLK	D13 complemented
(V_{IN}-V_{INB}) within range	H	L	L	CLK	D13
	L	L	L	CLK	D13 complemented
X	X	H	HZ[1]	HZ	HZ (all digital outputs are in high impedance)

1. High impedance.

3.8.1 Digital inputs

Data format select bit (DFSB): when set to low level (V_{IL}), the digital input DFSB provides a two's complement digital output MSB. This can be of interest when performing some further signal processing. When set to high level (V_{IH}), DFSB provides standard binary output coding (see *Table 12*).

Output enable bit (OEB): when set to low level (V_{IL}), all digital outputs remain active. When set to high level (V_{IH}), all digital output buffers are in a high impedance state while the converter goes on sampling. When OEB is set to a low level again, the data arrives on the output with a very short T_{on} delay. This feature enables the chip select of the device. *Figure 11: Timing diagram* summarizes this functionality.

Reference mode control (REFMODE): this allows the internal or external settings of the voltage references VREFP and INCM. REFMODE = 0 for internal references, REFMODE = 1 for external references (and disables both references VREFP and INCM).

3.8.2 Digital outputs

Out of range (OR): this function is implemented on the output stage in order to set an "out-of-range" flag whenever the digital data is over the full-scale range. Typically, there is a detection of all data at '0' or all data at '1'. It sets an output signal OR, which is in a low-level state (V_{OL}) when the data stays within the range, or in a high-level state (V_{OH}) when the data read by the ADC is out of range.

Data ready (DR): the Data Ready output is an image of the clock being synchronized on the output data (D0 to D13). This is a very helpful signal that simplifies the synchronization of the measurement equipment of the controlling DSP. Like all other digital outputs, DR goes into high impedance when OEB is set to a high level, as shown in *Figure 11: Timing diagram*.

3.8.3   Digital output load considerations

The features of the internal output buffers limit the maximum load on the digital data output. In particular, the shape and amplitude of the Data Ready signal, toggling at the clock frequency, can be weakened by a higher equivalent load.

In applications that impose higher load conditions, it is recommended to use the falling edge of the master clock instead of the Data Ready signal. This is possible because the output transitions are internally synchronized with the falling edge of the clock.

Figure 24. Output buffer fall time

Figure 25. Output buffer rise time
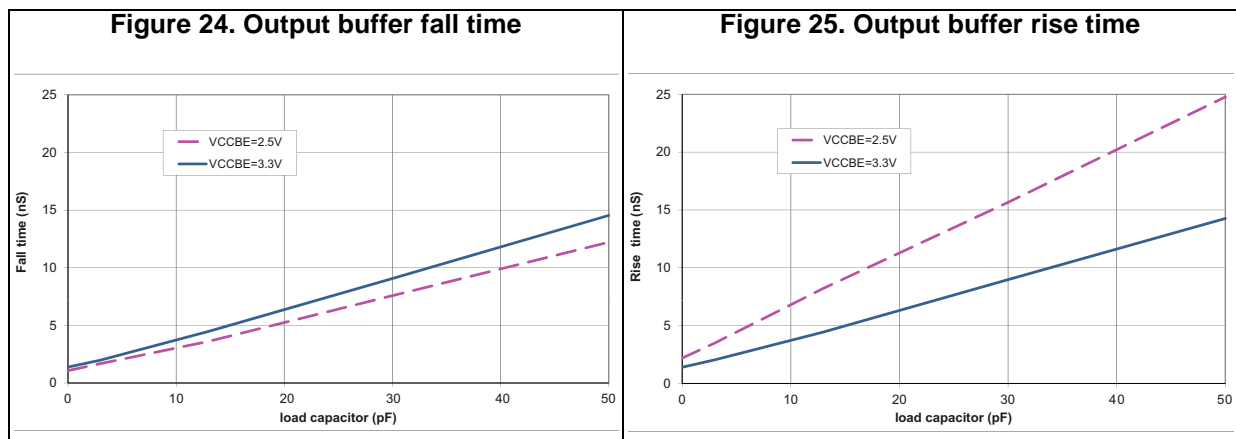
3.9   PCB layout precautions

- A ground plane on each layer of the PCB with multiple vias dedicated for inter connexion is recommended for high-speed circuit applications to provide low parasitic inductance and resistance. The goal is to have a "common ground plane" where AGND and DGND are connected with the lowest DC resistance and lowest AC impedance.

- To minimize the transition current when the output changes, the capacitive load at the digital outputs must be reduced as much as possible by using the shortest-possible routing tracks. One way to reduce the capacitive load is to remove the ground plane under the output digital pins and layers at high sampling frequencies.

- The separation of the analog signal from the clock signal and digital outputs is mandatory to prevent noise from coupling onto the input signal.

- Power supply bypass capacitors must be placed as close as possible to the IC pins to improve high-frequency bypassing and reduce harmonic distortion.

- All leads must be as short as possible, especially for the analog input, so as to decrease parasitic capacitance and inductance.

- Choose the smallest-possible component sizes (SMD).

4 Definitions of specified parameters

4.1 Static parameters

Differential non-linearity (DNL)

The average deviation of any output code width from the ideal code width of 1 LSB.

Integral non-linearity (INL)

An ideal converter exhibits a transfer function that is a straight line from the starting code to the ending code. The INL is the deviation from this ideal line for each transition.

4.2 Dynamic parameters

Spurious free dynamic range (SFDR)

The ratio between the power of the worst spurious signal (not always a harmonic) and the amplitude of the fundamental tone (signal power) over the full Nyquist band. Expressed in dBc.

Total harmonic distortion (THD)

The ratio of the rms sum of the first five harmonic distortion components to the rms value of the fundamental line. Expressed in dB.

Signal-to-noise ratio (SNR)

The ratio of the rms value of the fundamental component to the rms sum of all other spectral components in the Nyquist band ($F_s/2$) excluding DC, fundamental and the first five harmonics. Expressed in dB.

Signal-to-noise and distortion ratio (SINAD)

A similar ratio to the SNR but that includes the harmonic distortion components in the noise figure (not the DC signal). Expressed in dB. From SINAD, the effective number of bits (ENOB) can easily be deduced using the formula:

$$SINAD = 6.02 \times ENOB + 1.76 \text{ dB}$$

When the analog input signal is not full scale (FS) but has an A_0 amplitude, the SINAD expression becomes:

$$SINAD = 6.02 \times ENOB + 1.76 \text{ dB} + 20 \log (A_0 / FS)$$

Analog input bandwidth

The maximum analog input frequency at which the spectral response of a full power signal is reduced by 3 dB. Higher values can be achieved with smaller input levels.

Pipeline delay

The delay between the initial sample of the analog input and the availability of the corresponding digital data output on the output bus. Also called data latency. Expressed as a number of clock cycles.

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Figure 26. Ceramic SO-48 package mechanical drawing
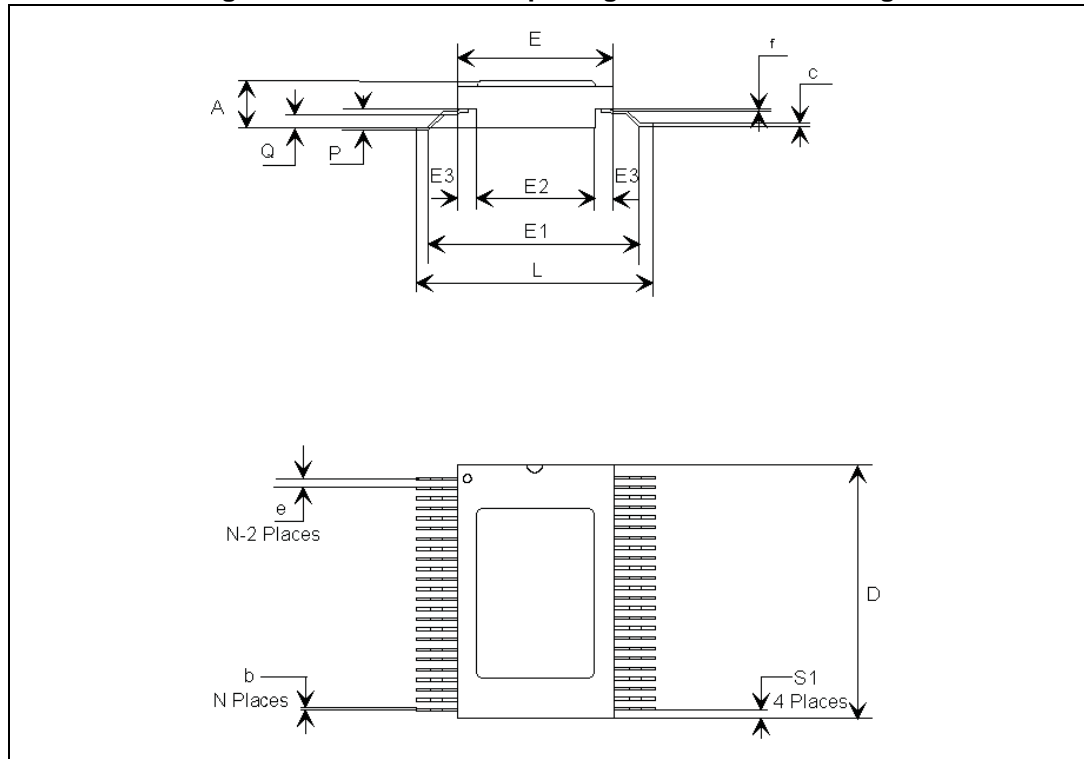
Note: *The upper metallic lid is not electrically connected to any pins, nor to the IC die inside the package. Connecting unused pins or metal lid to ground or to the power supply will not affect the electrical characteristics.*

Table 15. Ceramic SO-48 package mechanical data

Ref.	Dimensions					
	Millimeters			**Inches**		
	Min.	**Typ.**	**Max.**	**Min.**	**Typ.**	**Max.**
A	2.18	2.47	2.72	0.086	0.097	0.107
b	0.20	0.254	0.30	0.008	0.010	0.012
c	0.12	0.15	0.18	0.005	0.006	0.007
D	15.57	15.75	15.92	0.613	0.620	0.627
E	9.52	9.65	9.78	0.375	0.380	0.385
E1		10.90			0.429	
E2	6.22	6.35	6.48	0.245	0.250	0.255
E3	1.52	1.65	1.78	0.060	0.065	0.070
e		0.635			0.025	
f		0.20			0.008	
L	12.28	12.58	12.88	0.483	0.495	0.507
P	1.30	1.45	1.60	0.051	0.057	0.063
Q	0.66	0.79	0.92	0.026	0.031	0.036
S1	0.25	0.43	0.61	0.010	0.017	0.024

6   Ordering information

Table 16. Order codes

Order code	Description	Temp. range	Package	Marking [1]	Packing
RHF1401KSO1	Engineering model	-55 °C to 125 °C	SO-48	RHF1401KSO1	Strip pack
RHF1401KSO-01V	QML-V flight			5962F0626001VXC	

1.   Specific marking only. Complete marking includes the following:
      - SMD pin (for QML flight only)
      - ST logo
      - Date code (date the package was sealed) in YYWWA (year, week, and lot index of week)
      - QML logo (Q or V)
      - Country of origin (FR = France)

Note: Contact your ST sales office for information regarding the specific conditions for products in die form and QML-Q versions.

7 Other information

7.1 Date code

The date code is structured as shown below:

- Engineering model: EM xyywwz
- QML flight model: FM yywwz

Where:

x (EM only): 3, assembly location Rennes (France)

yy: last two digits year

ww: week digits

z: lot index in the week

7.2 Documentation

Table 17. Documentation provided for QMLV flight

Quality level	Documentation
Engineering model	
QML-V flight	– Certificate of conformance with Group C (reliability test) and group D (package qualification) reference – Precap report – PIND[1] test summary (test method conformance certificate) – SEM[2] report – X-ray report – Screening summary – Failed component list (list of components that have failed during screening) – Group A summary (QCI[3] electrical test) – Group B summary (QCI[3] mechanical test) – Group E (QCI[3] wafer lot radiation test)

1. PIND = particle impact noise detection

2. SEM = scanning electron microscope

3. QCI = quality conformance inspection

8 Revision history

Table 18. Document revision history

Date	Revision	Changes
29-Jun-2007	1	First public release. Failure immune and latchup immune value increased to 120 MeV-cm2/mg. Updated package mechanical information. Removed reference to non rad-hard components from External references, common mode: on page 16.
29-Oct-2007	2	Updated Figure 1: RHF1401 block diagram. Added explanation on Figure 3: Timing diagram. Added introduction to Section 6: Typical performance characteristics. Updated Section 7.2: Clock signal requirements and Section 7.3: Power consumption optimization. Added Section 7.4: Low sampling rate recommendations. Updated information on Data Ready signal in Section 7.5: Digital inputs/outputs. Added Figure 24: Impact of clock frequency on RHF1401 performance and Figure 25: CLK signal derivation.
09-Nov-2009	3	Changed input clock features in Table 10. Modified Table 14. Added Figure 24 to Figure 42.
26-Feb-2010	4	Modified Figure 1: RHF1401 block diagram. Added details for Tdr and changed values for Tpd in Table 5: Timing characteristics. Modified Figure 11: Timing diagram. Changed values for VREFP in Table 4. Changed Vin operating conditions in Table 4, Figure 42 and Figure 19. Changed values for DNL in Table 9.
13-Sep-2010	5	Modified Figure 1 on page 6 and Figure 9 on page 10. Added note 2. on page 12. Modified CIN typ value in Table 6: Analog inputs as per Figure 3. Modified Figure 11: Timing diagram. Replaced Figure 18. Added Table 12: Output codes for DFSB = 1. Modified Figure 17: Example 2 Vpp differential input.
29-Jul-2011	6	Added Note: on page 31 and in the "Pin connections" diagram on the cover page.

Table 18. Document revision history (continued)

Date	Revision	Changes
06-Apr-2012	7	Added Table 1: Device summary on cover page. Updated curves in Section 2.3: Electrical characteristics (after 300 kRad). Modified Section 3.1: Optimizing the power consumption. Modified Section 3.2: Driving the analog input: How to correctly bias the RHF1401. Modified Section 3.5.1: Internal voltage reference. Modified Section 3.5.2: External voltage reference. Modified Section 3.9: PCB layout precautions.
24-Oct-2012	8	Updated Table 1 Modified Figure 1: RHF1401 block diagram Modified Figure 4: Output buffers Modified Table 4, Table 7, and Table 8 Modified Section 2.4: Results for differential input Modified Section 2.5: Results for single ended input Added comments and changed layout of Section 3.2: Driving the analog input: How to correctly bias the RHF1401. Modified Table 12 Modified Figure 19 Added Table 13 Added comments to Section 3.5: Reference connections Modified Section 3.8.1: Digital inputs.
22-July-2014	9	Modified Figure 3 Modified Table 4 Modified Table 6 Modified Table 8 Added OE and GE in Table 9 Rewording and new Section 3.1: Optimizing the power consumption, Section 3.2: Driving the analog input: How to correctly bias the RHF1401, Section 3.3: Output code vs. analog input and mode usage, Section 3.4: Design examples, Section 3.5: Reference connections, Section 3.6: Clock input, Section 3.7: Reset of RHF1401, Section 3.9: PCB layout precautions Added footnote 1 to Table 6 Added Section 7: Other information.
12-Dec-2017	10	Updated the description in cover page. Deleted EPPL parameter in the *Table 1: Device summary*.

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